Overview

HP ProBook 450 G6 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Webcam
- 3. Webcam LED
- 4. Clickpad
- 5. Hard Drive LED

- 6. SD Card Reader
- 7. Thermal Vent
- 8. USB 2.0 Port
- 9. Standard Security Lock Slot (Lock sold separately)
- 10. Power Button



Overview



Right

- 1. Power Connector
- 2. USB Type-C[™] 3.1 Gen 1 Port
- 3. Ethernet Port (RJ-45)
- 4. HDMI Port (Cable not included)

- 5. USB 3.1 Gen 1 Port
- 6. USB 3.1 Gen 1 Port
- 7. Headphone/Microphone Combo Jack
- 8. HP Fingerprint Sensor (select models)



Overview

At a Glance

- Preinstall with Windows 10 versions or FreeDOS 3.0
- Choice of 8th Generation Intel[®] Core[™] i7, i5, i3 processors
- Display include your choice of 39.62 cm (15.6") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch
- Optional Nvidia GeForce MX250 and MX130 with 2 GB GDDR5 dedicated video memory or integrated Intel[®] HD Graphics 610 or Intel[®] UHD 620
- Enhanced security features including TPM2.0, HP BIOSphere, Hardware enforced Firmware Protection, HP Fingerprint Sensor³ (select models) and IR camera
- Passed 19 items of MIL-STD 810G testing plus an additional 120,000 hours of reliability testing through HP's Total Test Process¹
- Weight starting at 4.41 lbs (2.0 kgs)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Supports wireless LAN and wireless WWAN options for connectivity on the go
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard with numeric keypad, and Clickpad with multi-touch gestures enabled, taps enabled as default.
- Enjoy the rich conferencing experience of the Skype for Business™ Certified HP ProBook 450
- MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.
- 3. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAMES

HP ProBook 450 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ Windows 10 China Government Edition FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel[®] Core™ i7-8565U processor with Intel[®] UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-8265U with Intel[®] UHD Graphics 620 Graphics (1.6 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores) ^{3,4,5,6}

Intel[®] Core[™] i5-8365U vPro[™] processor with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i3-8145U with Intel[®] UHD Graphics 620 Graphics (2.1 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 4 MB L3 cache, 2 cores) ^{3,4,5,6}

Intel[®] Core[™] i7+ 8565U processor (Core[™] i7 and 16 GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel[®] Core[™] i5+ 8265U processor (Core[™] i5 and 16 GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores) ^{3,4,5,6,7}

Intel[®] Celeron[®] 4205U processor with Intel[®] HD Graphics 610 (1.8 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6} Intel[®] Pentium[®] 5405U processor with Intel[®] HD Graphics 610 (2.3 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6}

Processors Family

8th Generation Intel[®] Core[™] i7 processor (i7-8565U)⁶ 8th Generation Intel[®] Core[™] i5 processor (i5-8265U, 8365U)⁶ 8th Generation Intel[®] Core[™] i3 processor (i3-8145U)⁶ Intel[®] Pentium[®] processor (5405U)⁶ Intel[®] Celeron[®] processor (4205U)⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



Technical Specifications

- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
- 7. Intel[®] Optane[™] memory system acceleration does not replace or increase the DRAM in your system and requires configuration with an optional Intel[®] Core[™] i(5 or 7)+ processor.

CHIPSET

Integrated with processor

GRAPHICS

Integrated Intel[®] UHD graphics 620⁸

Discrete

NVIDIA® GeForce® MX130 (2 GB DDR5 dedicated)⁹ NVIDIA® GeForce® MX250 (2 GB DDR5 dedicated)⁹

Supports

Support HD decode, DX12, HDMI 1.4b up to 4K 30Hz Support CUDA, Optimus, PhysX, GPU Boost 2.0

- 8. HD content required to view HD images.
- 9. Integrated graphics depends on processor. NVIDIA® Optimus™ technology requires an Intel processor, plus an NVIDIA® GeForce® discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® Optimus™ technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAYS

Internal

Non-Touch

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for two WLAN antennas (1366 x 768)^{8,10}

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and one WLAN antenna (1366 x 768)^{8,10}

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1366 x 768)^{8,10}

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD+IR camera and two WLAN antennas (1366 x 768)^{8,10}

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768)^{8,10}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for two WLAN antennas (1920 x 1080)^{8,10}



Technical Specifications

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and one WLAN antenna (1920 x 1080)^{8,10}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1920 x 1080)^{8,10}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD+IR camera and two WLAN antennas (1920 x 1080)^{8,10}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080)^{8,10}

Touch

39.6 cm (15.6") diagonal HD SVA eDP LED-backlit slim touch screen, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1366 x 768)^{8,10,11}

39.6 cm (15.6") diagonal HD SVA eDP LED-backlit slim touch screen, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768)^{8,10,11}

HDMI

Supports resolutions up to 4K 30Hz

8. HD content required to view HD images.

- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. Sold separately or as an optional feature.

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB,1xUSB-C alt- mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary Storage 500 GB 7200 rpm SATA¹² 1 TB 5400 rpm SATA¹² 1 TB 7200 rpm SATA (LA Only)¹²



Primary M.2 Storage

128 GB M.2 SATA TLC Solid State Drive¹² 256 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹² 512 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹² 512 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹² 1 TB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹²

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

Note: PCIe SSD not available for Celeron

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM¹³

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹³ 16 GB DDR4- 2400 SDRAM (1 X 16 GB) 16 GB DDR4- 2400 SDRAM (2 X 8 GB)¹³ 12 GB DDR4- 2400 SDRAM (4 GB and 8 GB (1 x 8 GB)¹³ 8 GB DDR4- 2400 SDRAM (1 x 8 GB) 8 GB DDR4- 2400 SDRAM (2 x 4 GB)¹³ 4 GB DDR4- 2400 SDRAM (1 x 4 GB)

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel[®] Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth[®] 5.0 Combo, non-vPro^{™14} Realtek RTL8821CE 802.11a/b/g/n/ac (1x1) WLAN + Bluetooth[®]4.2 Combo¹⁴ Realtek RTL8822BE 802.11a/b/g/n/ac (2x2) WLAN + Bluetooth[®]4.2 Combo¹⁴

WWAN

Intel[®] XMM[™] 7262 LTE-Advanced (Cat6)¹⁵ Intel[®] XMM[™] 7360 LTE-Advanced (Cat9)¹⁵

Ethernet

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC¹⁶

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications



Technical Specifications

differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

- 15. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 16. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Integrated Microphone (Mono or Dual Array) 2 Integrated Stereo Speakers

Speaker Power 2W/4ohm per Speaker

Camera 720p HD Camera⁸ 720p HD Camera+IR Camera^{8,17}

8. HD content required to view HD images.

17. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device Clickpad with multi-touch gesture support

Function Keys

- F1 Display Switching
- F2 Blank
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Blank
- F11 Wireless
- F12 Sleep

Hidden Functions

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock



Technical Specifications

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen4¹⁸ HP DriveLock & Automatic DriveLock BIOS Update via Network Secure Erase¹⁹ Absolute Persistence Module²⁰ Pre-boot Authentication HP Wireless Wakeup

Software

HP Native Miracast Support²¹ HP LAN-Wireless Protection HP Connection Optimizer HP 3D DriveGuard HP Hotkey Support - CMIT HP Jumpstart HP Support Assistant²² HP Noise Cancellation Software HP Host Based MAC Address Manager Buy Office (sold separately)

Manageability Features

HP Driver Packs²³ HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen2²⁴ Ivanti Management Suite²⁵ HP Cloud Recovery²⁶

Client Security Software

HP Client Security Suite Gen4²⁷ including: HP Security Manager²⁸ (including Credential Manager, HP Password Manager, HP Spare Key) HP Device Access Manager²⁹ HP Power On Authentication HP Fingerprint Sensor (select models)³⁴ Windows Defender³⁰



Security Management

Secure Erase¹⁹

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³¹

SATA 0,1 port disablement (viaBIOS)

RAID configurations³²

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click³³

- 18. HP BIOSphere Gen4 requires Intel(R) or AMD 8th Gen processors. Features may vary depending on the platform and configurations.
- 19. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 20. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void.

optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 22. HP Support Assistant requires Windows and Internet access.
- 23. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 24. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 25. Ivanti Management Suite subscription required.
- 26. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 27. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
- 28. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 29. HP Device Access Manager requires HP Client Security Suite Gen4.
- 30. Windows Defender Opt in and internet connection required for updates.
- 31. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 32. RAID configuration is optional and does require a second hard drive.
- 33. HP Sure Click is available on most HP PCs and supports Microsoft[®] Internet Explorer and Chromium[™]. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode when Microsoft Office or Adobe Acrobat are installed.
- 34. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.



POWER

Power Supply

HP Smart 65 W External AC power adapter³⁵ HP Smart 65 W EM External AC power adapter³⁵ HP Smart 65 W USB Type-C[™] adapter³⁵ HP Smart 45 W External AC power adapter³⁵ HP Smart 45 W USB Type-C[™] adapter³⁵

Primary Battery HP Long Life 3-cell, 45 Wh Polymer³⁶

Battery Life Up to 12 hours and 30 minutes³⁷

Power Cord

3-wire plug - 1m³⁵ 3-wire plug - 1.8m³⁵ 2-wire plug - 1m³⁵ Duckhead power cord- 1.0m³⁵ Duckhead power cord- 1.8m³⁵

Battery Weight

0.49 lb 0.22 kg

- 35. Availability may vary by country.
- 36. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 37. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 4.41 lbs³⁸ Starting at 2.0 kgs³⁸

Dimensions (w x d x h)

14.37 x 10.11 x 0.75 in 36.49 x 25.69 x 1.9 cm

38. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C[™] Gen 1 (Power delivery, DisplayPort[™] 1.2) 1 USB 2.0 (Powered port) 2 USB 3.1 1 HDMI 1.4b³⁹ 1 RJ-45 1 AC power



1 Headphone/microphone combo jack

Expansion Slots 1 SD Supports SD, SDHC, SDXC

39. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴⁰

40. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

ENVIRONMENTAL & INDUSTRY

HP Probook 450 G6 Notebook PC

Eco-Label Certifications	This product has received or is in t	This product has received or is in the process of being certified to the following approvals and may		
& declarations	be labeled with one or more of the	ese marks:		
	•IT ECO declaration •US ENERGY STAR®			
	•EPEAT [®] Silver registered in the U	nited States. See http://www.epeat.	net for registration status in	
	your country.			
	•TCO or TCO Certified Edge			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the			
	Notebook model is based on a Typ	Notebook model is based on a Typically Configured Notebook.		
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	5.97 W	5.86 W	5.96 W	
(Short idle)				
Normal Operation	2.96 W	3.14 W	3.00 W	
(Long idle)				
Sleep	0.79 W	0.81 W	0.79 W	
Off	0.39 W	0.42 W	0.39 W	
Energy efficiency data listed is for an ENERGY STAR [®] compliant product if offered within the family. HP computers marked with the ENERGY STAR [®] Logo are compliant with the applicabl				
	Environmental Protection Agency (EPA) ENERGY STAR [®] specifications for computers. If a model			
family does not offer ENERGY STAR [®] compliant configurations, then energy efficiency da				
	for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a			
	Microsoft Windows [®] operating sys	stem.	1	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	



Technical Specifications

Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes	3		11 BTU/hr <u>3 BTU/hr</u> 1 BTU/hr ed on the measured watts, a	ssuming the ser Sound Pr (L _{pAm} , de	
Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes	1 Heat dissipat	BTU/hr tion is calculated bas Sound Power (L _{WAd} , bels)	1 BTU/hr	Sound P	1 BTU/hr rvice level is attained
Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes	1 Heat dissipat	BTU/hr tion is calculated bas Sound Power (L _{WAd} , bels)	1 BTU/hr	Sound P	1 BTU/hr rvice level is attained
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes	Heat dissipat	tion is calculated bas Sound Power (L _{WAd} , bels)		Sound P	rvice level is attained
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Longevity and Upgrading		Sound Power (Lwad, bels)			ressure
(in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes				(L _{pAm} , de	
Idle Fixed Disk – Random writes		3			cibels)
writes			3 26.6		.6
Longevity and Upgrading		3 26.7		.7	
	 This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: 3 USB ports 2 SODIMM memory slots Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. 				
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC				
	Mercury grea Cadmium gre Battery size:	ed in the product do r ater the1ppm by weig eater than 20ppm by CR2032 (coin cell) : lithium/manganese	ght weight		
Additional Information	2011/65/EC. • This HP pro Directive – 20 • This produce Water and To • This produce http://www.u • Plastics par • This produce	duct is designed to c 002/96/EC. t is in compliance wi oxic Enforcement Act t is in compliance wi epeat.net rts weighing over 25 t contains 12.7% po	th the Restrictions of Hazard comply with the Waste Electri th California Proposition 65 (c of 1986). th the IEEE 1680.1 (EPEAT) s grams used in the product ar st-consumer recycled plastic ble when properly disposed o	cal and Electror State of Califorr tandard at the S e marked per IS (by wt.)	nic Equipment (WEEE) nia; Safe Drinking iilver level, see
Packaging Materials	External:	PAPER/Corrugated	d	295	g
	Internal:	PLASTIC/Polyethy	lene Expanded - EPE	68 g]
		PLASTIC/Polyethy	lene low density – LDPE	10 g	 /
Material Usage	to the HP Get http://www.l • Asbestos • Certain Azo • Certain Bro • Cadmium	does not contain an neral Specification fo hp.com/hpinfo/globa Colorants	y of the following substances or the Environment at alcitizenship/environment/po rdants – may not be used as f	lf/gse.pdf):	
	Chlorinated	Chlorinated Paraffins Not all configuration components are available in all regions/countries.			



Technical Specifications

	F auna a labelar a la
	• Formaldehyde
	 Halogenated Diphenyl Methanes Lead carbonates and sulfates
	Lead and Lead compounds Margurine Ovide Patteries
	Mercuric Oxide Batteries
	• Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs) Delubrominated Biphenyl Ethons (DBBEs)
	Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Ovides (BBBOs)
	 Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB)
	, , , , , , , , , , , , , , , , , , , ,
	Polychlorinated Terphenyls (PCT) Polyminul Chlorida (DVC) - overant for wires and cables, and certain retail paskaging has been
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances Tributul Tip (TDT) Tributul Tip Ovide (TDTO)
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	• Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



SYSTEM UNIT

Stand-Alone Power Requirements
(AC Power)

(Act ower)	
Nominal Operating Voltage	19V
Average Operating Power	Win 10
Integrated graphics	5.71W
Discrete Graphics	6.78W
Max Operating Power	Discrete < 65W
	UMA < 45W
Temperature	32° to 95° F (0° to 35° C)
Operating	-4° to 140° F (-20° to 60° C)
Non-operating Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grms
Non-operating	1.50 grms
Altitude (unpressurized)	
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard Certifications	
UL	Yes
CSA	Yes
FCC Compliance	Yes
Energy Star [®]	Selected models ⁴¹
EPEAT [®] 2019	Yes, Silver in U.S. ⁴²
ICES	Yes
Australia NZ A-Tick Compliance	Yes
	Yes
Japan VCCI Compliance	Yes Yes
KC	
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP)	Yes
Sudai Alabian compliance (ICCF)	Yes



SABS	Yes
UKRSERTCOMPUTER	Yes

- 41. Configurations of the HP ProBook 450 G6 that are ENERGY STAR[®] certified² are identified as HP ProBook 450 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.
- 42. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal	Outline Dimensions (W x H x D)	316.17 x 197.98 (max)
FHD (1920 x 1080) Anti- Glare WLED UWVA 45%	Active Area	309.37 x 174.02 (typ.)
NTSC 250 nits eDP slim	Weight	285 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85
Panel LCD 15.6 inch	Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)

Panel LCD 15.6 inch	Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)
diagonal FHD (1920 x 1080)		344.16 x 193.59 (typ.)
Anti-Glare WLED UWVA 45% cg 220nits eDP slim NB non-		<370 g max.
touch	Diagonal Size	15.6"
	Thickness	3.2 mm max.
	Interface	eDP 1.2
	Surface Treatment	Anti-glare
	Touch Enabled	No



Technical Specifications

	Contrast Ratio	600:1 (typ) - AG	
	Refresh Rate	60 Hz	
	Brightness	220 nits typical (Panel Only)	
	Pixel Resolution	1920 x 1080 (FHD)	
	Format	RGB	
	Backlight Color Gamut Coverage Color Depth	LED 45% 6 bits + Hi FRC	
	Viewing Angle	UWVA 85/85/85	
Panel LCD 15.6 inch	Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)	
diagonal HD (1366 x 768)	Active Area	344.16 x 193.59 (typ.)	
Anti-Glare WLED SVA 45% cg 220nits eDP 1.2 w/o PSR	Weight	<370 g max.	
slim NB non-touch	Diagonal Size	15.6"	
	Thickness	3.2 mm max.	
	Interface	eDP 1.2	
	Surface Treatment	Anti-glare	
	Touch Enabled	No	
	Contrast Ratio	300:1 (typ)	
	Refresh Rate	60 Hz	
	Brightness	220 nits typical (Panel Only)	
	Pixel Resolution	1366 x 768 (HD)	
	Format	RGB	
	Backlight	LED	
	Color Gamut Coverage	45%	
	Color Depth	6 bits + Hi FRC	

Panel LCD 15.6 inch diagonal HD (1366 x 768) WLED SVA 45% cg 220nits eDP 1.2 w/o PSR slim NB touch **Viewing Angle**

Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)
Active Area	344.16 x 193.59 (typ.)
Weight	<568 g max.
Diagonal Size	15.6"
Thickness	3.4 mm max.
Interface	eDP 1.2
Surface Treatment	BrightView Glass
Touch Enabled	Yes
Contrast Ratio	300:1 (typ)
Refresh Rate	60 Hz
Brightness	220 nits typical (Panel Only)
Pixel Resolution	1366 x 768 (HD)

SVA 40/40/15/30



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

Technical Specifications

Format	RGB
Backlight	LED
Color Gamut Coverage	45%
Color Depth	6 bits + Hi FRC
Viewing Angle	SVA 40/40/15/30

STORAGE AND DRIVES Hard Drives

Hard Drives		
500 GB 7200 rpm SATA Hard Drive	Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (95 g)
	Rotation speed	7200 rpm
	Cache Buffer	Up to 32 MB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track: 2 ~ 1.5 ms; Average: 11 ~ 13 ms; Maximum: 18 ~ 22 ms
	Logical Blocks	976,773,168
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA
1 TB 5400 rpm SATA Hard Drive	Drive Weight Rotation speed Cache Buffer Height	0.21 lbs (94 g) 5400 rpm Up to 32 MB 0.28 in (7.2 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track2 ms Average12 ~ 13 ms Maximum18 ~ 22 ms
	Logical Blocks	1,953,525,168
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA
SSD 128 GB 2280 M2 SATA-	Form Factor	M.2 2280
3 TLC	Capacity	128GB
	NAND Type	TLC
_		



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Up To 520 MB/s
	Maximum Sequential Write	Up To 450 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	DIPM; TRIM; DEVSLP
256 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value Solid State Drive	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	Up To 1700 MB/s
	Maximum Sequential Write	Up To 1300 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2
512 GB 2280 M2 PCIe NVMe TLC Solid State Drive		M.2 2280
TEC Solia State Drive	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Height Width	0.09 in (2.3 mm) 0.87 in (22 mm)
	Height Width Interface	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4
	Height Width Interface Maximum Sequential Read	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s
	Height Width Interface Maximum Sequential Read Maximum Sequential Write	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216
	Height Width Interface Maximum Sequential Read Maximum Sequential Write	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp]
16 GB 2280 PCIe-3x2 NVMe	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp]
16 GB 2280 PCIe-3x2 NVMe 3D Xpoint Solid State Drive	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features	0.09 in (2.3 mm) 0.87 in (22 mm) PCle NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features Form Factor Capacity	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2 M.2 2280 16 GB
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2 M.2 2280 16 GB Xpoint
	Height Width Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features Form Factor Capacity NAND Type Height	0.09 in (2.3 mm) 0.87 in (22 mm) PCIe NVMe Gen3X4 Up To 2600 MB/s Up To 1400 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2 M.2 2280 16 GB Xpoint 0.09 in (2.3 mm)



	Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features	1400 300 28,181,188 32° to 158°F (0° to 70°C) [ambient temp] L1.2
512 GB 2280 PCIe NVMe Value Solid State Drive	Form Factor Capacity	M.2 2280 512 GB
	NAND Type Height Width Interface	Value 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g)
	Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature	Up To 1500 ~ 1700 MB/s Up To 860 ~ 1500MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security, TRIM; L1.2



NETWORKING/COMMUNICATIONS

WWAN

Intel® XMM™ 7360 LTE- Advanced CAT9 ¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm
	1. WWAN module is	optional, must be configured at the factory and requires separately purchased

1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7262 LTE- Advanced DL CAT6¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 (Band 20), 700 (Band 28), HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to 300Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
	Maximum data rates	LTE: 300 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 830 mA (average) HSPA+: 1,100 mA (peak); 680 mA (average)



Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

WLAN

Intel® 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5.0 Combo ¹ non-vPro		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi [®] certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz
		802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi[®] compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

Technical Specifications

Network Architecture	Ad-hoc (Peer to	-	
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points 802.11b: +18.5dBm minimum 		
Output Power ²			
	• 802.11g: +17.5		
	• 802.11a: +18.5		
		(2.4GHz): +15.5dBm minimum	
		(2.4GHz): +14.5dBm minimum	
		(5GHz): +15.5dBm minimum (5GHz): +14.5dBm minimum	
		30(5GHz): +11.5dBm minimum	
		160(5GHz): +11.5dBm minimum	
Power Consumption	Transmit mode: Receive mode: 1		
		.o w 180 mW (WLAN Associated)	
	···· ··· · · · · · · ·	W (WLAN unassociated)	
	Connected Stand	lby/Modern Standby: 10mW	
	Radio disabled: 8	3 mW	
Power Management		ress compliant power management	
_	•	nt power saving mode	
Receiver Sensitivity ³		: -93.5dBm maximum	
	802.11b, 11Mbps : -84dBm maximum		
	802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -67dBm maximum		
		: -64dBm maximum	
		: -84dBm maximum	
_		: -59dBm maximum	
Antenna type		ntenna with spatial diversity, mounted in the display	
	enclosure Two embedded	dual band 2.4/5 GHz antennas are provided to the card to	
		IMO communications and Bluetooth communications	
Form Factor	••	MiniCard with CNVi Interface	
Dimensions	•	3 x 22.0 x 30.0 mm	
		67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.		
	2. Type 126: 1.3		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
-	Non-operating	–40° to 176° F (–40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Ra	dio OFF; LED White – Radio ON	
1. Check latest software/	driver release for ut	dates on supported security features.	

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



HP Integrated Module wit	h Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology
Bluetooth [®] Specification	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹
	BLE: 1 Mbps signaling data rate ¹ 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension
	FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek W 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 4.2 Combo¹

Wireless LAN Standards IEEE 802.1 IEEE 802.1 IEEE 802.1 IEEE 802.1 IEEE 802.1

Interoperability

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi[®] certified



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

Technical Specifications

Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz
	802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ³	 IEEE and WiFi[®] compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10 mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum



Antenna type	802.11ac, MCS9 High efficiency a enclosure Two embedded (: -84dBm maximum : -59dBm maximum Intenna with spatial diversity, mounted in the display dual band 2.4/5 GHz antennas are provided to the card to IIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2	MiniCard
Dimensions	Туре 2230: 2.3 х	22.0 x 30.0 mm
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Rad	dio OFF; LED White – Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.2 Wireless Technology

Bluetooth Specification	4.0/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹
	BLE: 1 Mbps signaling data rate ¹ 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

Technical Specifications

	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Realtek 802.11a/b/g/n/ac (1x1) WLAN and Bluetooth® 4.2 Combo ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz
		802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) components are available in all regions (countries



Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020

Roaming Output Power ²	IEEE 802.11 compliant roaming between access points • 802.11b: +14dBm minimum • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum • 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum		
Power Consumption	Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10 mW Radio disabled 8 mW		
Power Management		ress compliant power management It power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Туре 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C) Non-operating –40° to 176° F (–40° to 80° C)		
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Rac	lio OFF; LED White – Radio ON	
1. Charle latest software (driver values a few values are supported as write factures			

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology			
Bluetooth Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Legacy: 0~79 (1 MHz/CH)			
Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 19 — April 22, 2020			



Channels Signaling Data Rate	BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps signaling data rate ¹ BLE: 1 Mbps signaling data rate ¹ 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

POWER

HP 45W Smart AC adapter	Dimensions (H x W x D)	3.74 x 1.57 x 1.04 in (9.5 x 4.0 x	x 2.65 cm)
	Weight	0.386 lb (175g) max	
	Input	90 to 265 VAC	
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 to 63 Hz



Technical Specifications

-			
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45W
		DC output	19.5V
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type, 3 pin/	grounded, mates with interchangeable cords
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety	*CE Mark - full compliance	with LVD and EMC directives
	Certifications		nds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE.
		* MTBF - over 200,000 hou	urs at 25°C ambient condition.
HP 65W Smart AC adapter	Dimensions	90x51x28.5mm	
•	Weight	unit: 220g +/- 10g	
	Input	Input Efficiency	88% min at 115 VAC and 89% min at 230 VA
	•	Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<11.0A
	Connector	-	grounded, mates with interchangeable cords
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		-	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety	*CE Mark - full compliance	with LVD and EMC directives
Certifications	Certifications	•	ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B,



FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

	o min at 115V/230V 0 63 Hz		
Input Input Efficiency 87%			
Input frequency range 47 to	o 63 Hz		
Input AC current 1.7 A	A at 90 VAC and maximum load		
DC output 65W	(19.5V/3.33A)		
Hold-up time 5 ms	sec at 115 VAC input		
	A, Over voltage protection- 29V max matic shutdown		
Connector 4.5mm Barrel Type, 3 pin/groun	nded, mates with interchangeable cords		
Environmental Design Operating 0° to to to the temperature	35° C		
Non-operating (storage) -20° temperature	to 85° C		
Altitude 0 to	5,000 m		
Humidity 0% t	o 95%		
Storage Humidity 0% t	o 95%		
EMI and Safety *CE Mark - full compliance with	LVD and EMC directives		
SELV; Agency approvals - C-UL- FCC Class B, CISPR22 Class B, CC	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		
AC Adapter 65 Watt nPFC Dimensions 74x74x28.5mm			
USB type C Weight unit: 245g +/- 10g			
86.7 88% 88% 88% 89%	5% min at 115 Vac/ 230Vac @ 5V/3A 7% min at 115 Vac/ 230Vac @ 9V/3A 6 min at 115 Vac/ 230Vac @ 10V/5A 6 min at 115 Vac/ 230Vac @ 12V/5A 6 min at 115 Vac/ 230Vac @ 15V/4.33A 6 min at 115 Vac/ 230Vac @ 20V/3.25A		
Input frequency range 47 to	o 63 Hz		
Input AC current 1.7 A	A at 90 VAC and maximum load		
Output power 65W			
DC output 5V/9	0V/10V/12V/15V/20V		
Hold-up time 5ms	at 115 Vac input		
Output current limit <8.0	A		
Connector Type C			
Environmental Design Operating 0° to to temperature	935° C		



Technical Specifi	cations		
		Non-operating (storage) temperature	-20° to 85° C
		Altitude	0 to 5,000 m
		Humidity	0% to 95%
		Storage Humidity	0% to 95%
	EMI and Safety	*CE Mark - full compliance	e with LVD and EMC directives
	Certifications		ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE.
		* MTBF - over 200,000 ho	urs at 25°C ambient condition.
AC Adapter 45 Watt nPFC	Dimensions	62.0x62.0x28.5mm	
USB type C	Weight	unit: 220g +/- 10g	
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec:5V: 81.5%9V: 86.7%10V : 87.5%12V : 87.8%15V: 87.8%20V: 87.8%
		Input frequency range	47 to 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
		Output power	5V/15W 9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<5.0A
	Connector	Туре С	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
	EMI and Safety Certifications	Storage Humidity	10% to 95%
		*CE Mark - full compliance	with LVD and EMC directives
			ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE.
		* MTBF - over 200,000 ho	urs at 25°C ambient condition.



Technical Specifications

3 Cell WHr 45 Long Life -	Dimensions (H x W x L)	6.0. x184.7x88.9 mm
Polymer HP Fast Charge Technology ¹	Weight	0.22 kg (0.48lb)
recumotogy	Cells/Type	3cell Lithium-Ion
	Voltage	11.55V
	Amp-hour capacity	3.900Ah
	Watt-hour capacity	45Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP Essential Messenger Case	H1D25AA
Dockings	HP USB-C Mini Dock	1PM64AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
Memory	4GB 2666MHz DDR4	4VN05AA
	8GB 2666MHz DDR4	4VN06AA
	16GB 2666 MHz DDR4	4VN07AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Power Adapter	3PN48AA
	HP 45W USB-C Power Adapter	1HE17AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP Power Bank	N9F71AA
	HP USB-C Power Bank	2NA10AA
	HP 45W LC USB-C Power Adapter	1MZ01AA#ABA
Storage	HP External USB Optical Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
Security	HP Combination Lock	TOY15AA
	HP Essential Keyed Cable lock 12.3mm	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP UltraSlim Keyed Cable Lock	T1A62AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP Speaker Phone	K7V16AA
	HP Wired Headset	K7V17AA
Displays	HP ProDisplay P223 21.5-inch Monitor	X7R61AA
	HP ProDisplay P232 23-inch Monitor	K7X31AA
	HP ProDisplay P240va 23.8-inch Monitor	X3B48AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E243m 23.8-inch Collaboration Monitor	1FH48AA
	HP EliteDisplay E273 27-inch Monitor	1FH50AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 10, 2018	V1 to V2	Removed	Dock UltraSlim
December 12, 2018	V2 to V3	Removed	Phonewise Software
December 17, 2018	V3 to V4	Added	Environmental Section
December 21, 2018	V4 to V5	Added	Skype in at a glance section
March 7, 2019	V5 to v6	Updated	Passed MIL-STD
March 15, 2019	V6 to V7	Added	Processors
March 27, 2019	V7 to V8	Updated	Storage and drives and Graphic section
April 17, 2019	V8 to V9	Updated	MIL-STD
May 7, 2019	V9 to V10	Updated	At a glance section
June 11, 2019	V10 to V11	Added	HP Cloud Recovery
July 22, 2019	V11 to V12	Added	Speaker Power
September 20, 2019	V12 to V13	Updated	1TB 7200 rpm SATA (LA Only), Lock Slot and 250nits Panel
September 24, 2019	V13 to V14	Added	1TB PCle® to Storage and Drives Section
October 11, 2019	V14 to V15	Added	DisplayPort™ 1.2 and i5-8365U Processor
November 21, 2019	V15 to V16	Updated	Longevity and Upgrading section
January 13, 2020	V16 to V17	Updated	Primary Battery
February 27, 2020	V17 to V18	Updated	Copyright and footnote for fingerprint sensor.
April 22, 2020	V18 to V19	Updated	Networking / Communications section

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